



$T_C=25$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	20	V
Continuous Drain Current	$I_D@T_C=25$	320	A
	$I_D@T_C=75$	243	A
	$I_D@T_C=100$	201	A
Pulsed Drain Current	I_{DM}	960	A
Total Power Dissipation	$P_D@T_C=25$	150	W
Total Power Dissipation	$P_D@T_A=25$	4.1	W

Operating Junction



Thermal resistance

Parameter

Discharge Time	t_b	VDD = 20 V, dIS/dt = 100 A/s, IS = 30 A	10.5	ns
Reverse Recovery Charge	Q_{RR}		15	ns

Note: ;

Fig.1 Power Dissipation

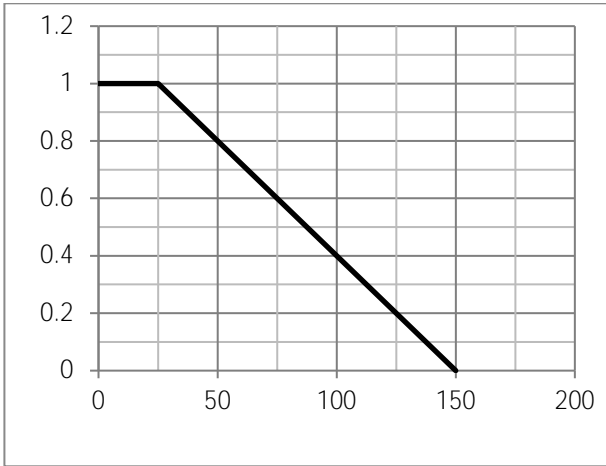


Fig.2 Typical output Characteristics

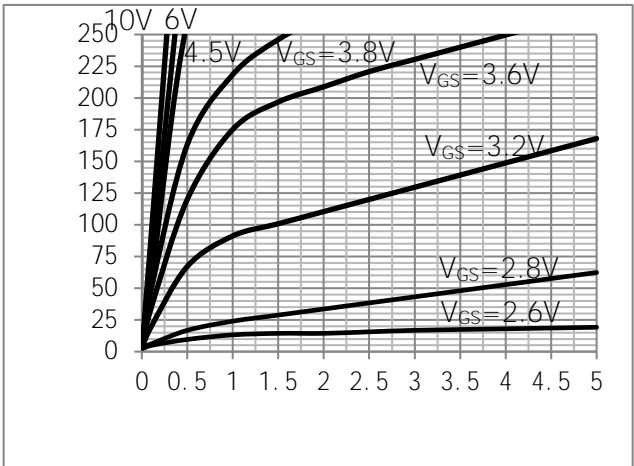


Fig.3 Threshold Voltage V.S Junction Temperature

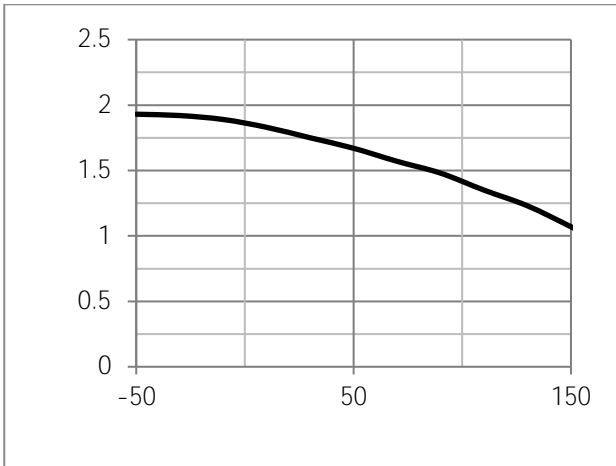


Fig.4 Resistance V.S Drain Current

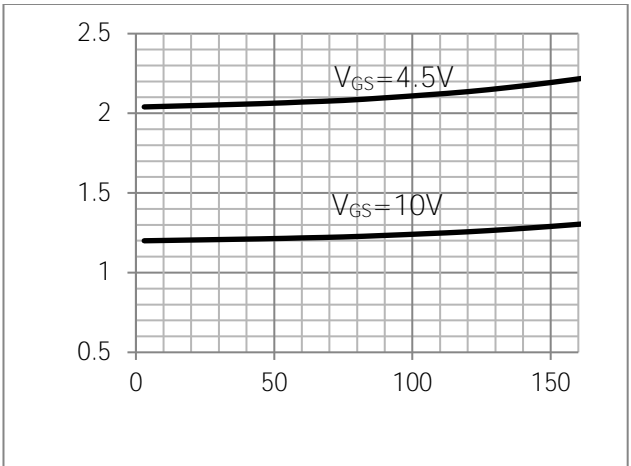


Fig.5 On-Resistance VS Gate Source Voltage

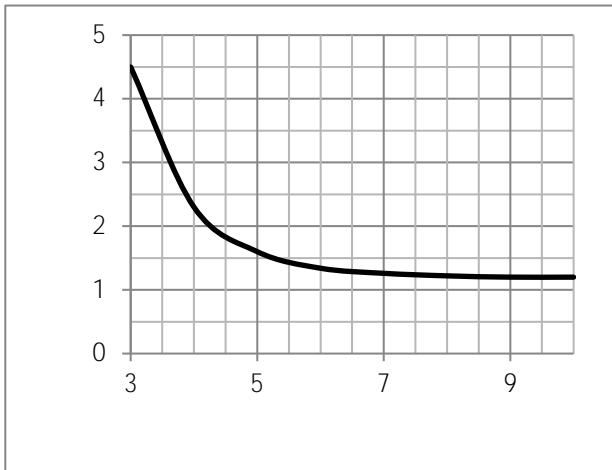


Fig.6 On-Resistance V.S Junction Temperature

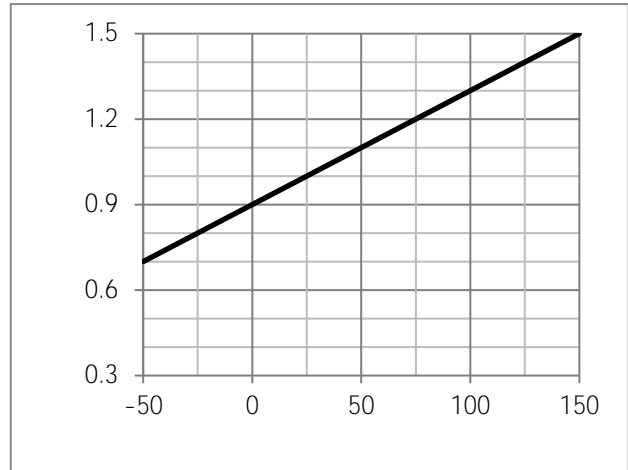


Fig.7 Gate Charge Characteristics

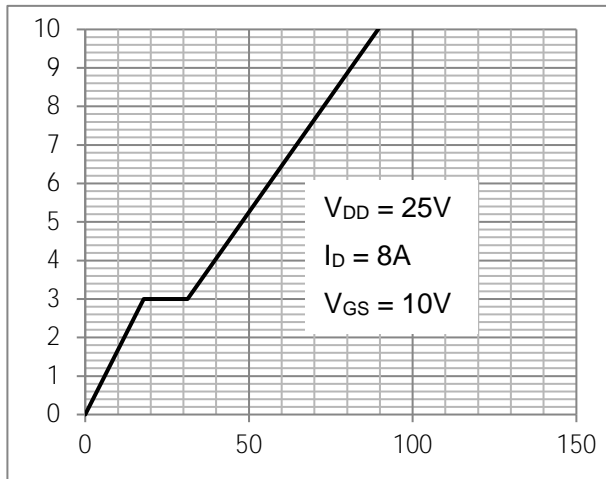


Fig.8 Capacitance vs V_{DS}

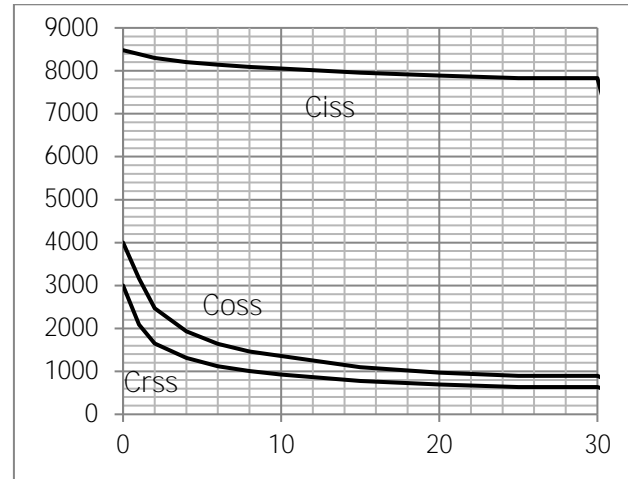


Fig.9 SOA Maximum Safe Operating Area

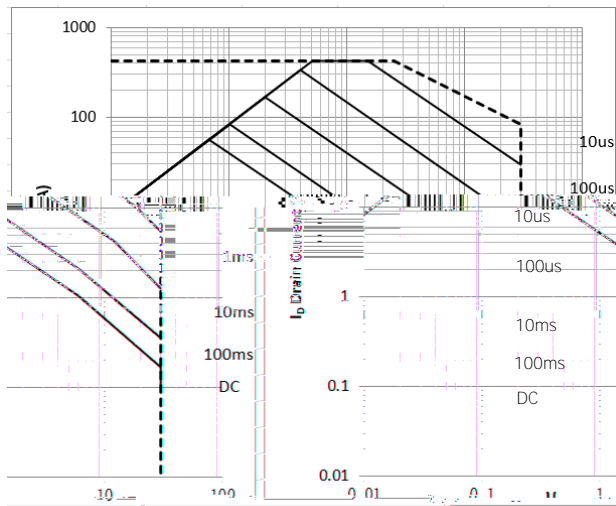
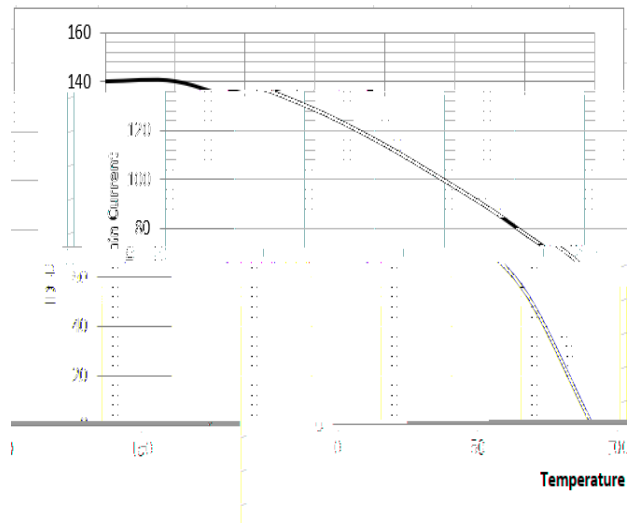


Fig.10 I_D -Junction Temperature



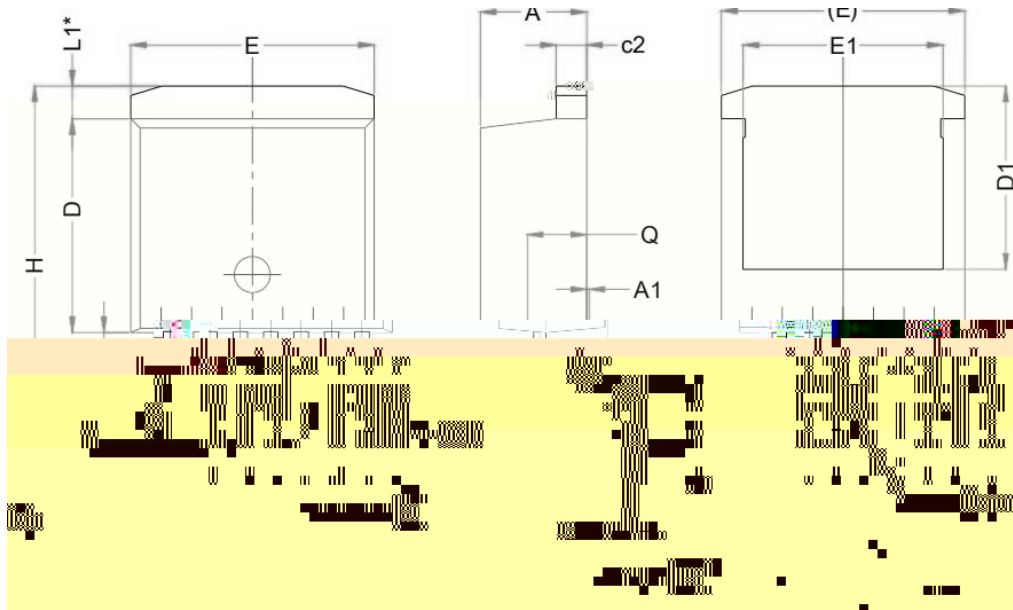






Dimensions (TO-263-6)

Unit mm



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25

0.50	0.60	c	0.40
1.27	1.40	c2	1.15
8.92	9.02	D	8.82
7.65		D1	6.86
10.16	10.36	E	9.96
8.35	8.50	E1	8.20
1.27 BSC		e	
14.61	15.00	15.88	+1.0
1.78	2.32	2.79	L
	1.36 REF.		L1
	1.50 REF.		L2
	0.25 BSC		L3

